Product End-of-Life Disassembly Instructions

Product Category: Notebooks

Marketing Name / Model
[List multiple models if applicable.]

HP Pavilion Notebook PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP's Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td></td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td></td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [x] screws [x] snaps [0] adhesive [0] other. Explain. NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC Cable for External Power Supply</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs)</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

HPI instructions for this template are available at EL-MF877-01
<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td>#1</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

#### 3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Dis-fasten BASE screw*10
2. Remove BASE
3. Pull out FFC*5 (Power, HDD, Touchpad, Keyboard Membrane, Keyboard BLK)
4. Remove HDD
5. Pull out wire cable *6 (LCD, WLAN, SPEAKER, FAN, Battery)
6. Dis-fasten Battery screw *4
7. Remove Battery module
8. Pull out USB FFC*2
9. Dis-fasten USB board screw *2
10. Remove USB board
11. Dis-fasten WLAN boards screw *1
12. Remove WLAN boards
13. Dis-fasten Hinge screw*6
14. Dis-fasten Power boards screw *1
15. Remove Power boards*1
16. Pull out DC IN Cable
17. Dis-fasten Fan screw *3
18. Remove Fan & Memory
19. Dis-fasten thermal module screw*6
20. Remove thermal module
21. Dis-fasten motherboard screw*1

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22. Remove motherboard
23. Dis-fasten TP Support BKT screw *3
24. Remove TP Support BKT
25. Dis-fasten Touchpad module screw *3
26. Remove Touchpad module
27. Remove speaker -L & -R
28. Remove DC Cable
29. Remove LCD Bezel
30. Dis-fasten LCD module screw*4
31. Pull out LCD cable & Camera cable
32. Remove LCD module
33. Remove Camera module
34. Dis-fasten Hinge screw*8
35. Remove Hinge -L & -R
36. Remove Antenna cable
37. Remove LCD cable

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Total part disassembly

2. Remove BASE assy.
3. Remove Wireless card & USB board & Card board & Memory & HDD

4. Remove motherboard & speaker & DC Cable & FAN & Thermal Module.
5. Remove Power board & TP Support BKT & Touchpad module.

6. Remove LCD bezel
7. Remove Panel

8. Remove Hinge -L & -R & Camera module & LCD cable & Antenna cables